RFC Reader / BSU IO

Table of Contents

Sheet 1: Title Page

Sheet 2: Reader Top Level Hierarchy

Sheet 3: Power Hierarchy Blocks

Sheet 4: POE and External DC Power

Sheet 5: DC/DC Converters and Regulators

Sheet 6: Digital Hierarchy Blocks

Sheet 7: Ethernet Phy Circuits

Sheet 8: Microcontroller

Sheet 9: Phytec SOM Connection Pinout

Sheet 10: RF Hierarchy Blocks

Sheet 11: AMS C1Gen2 RFID ASIC

Sheet 12: Reader Receive Channel

Sheet 13: Transmit RF Amplifiers

Sheet 14: RF Tuning Circuitry

Controlled Impedances

Equal Length =

USB 90ohm Diff. Pair

ISO= 50 mil - 0.050"

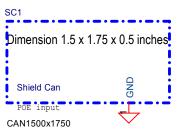
W= 16 mil Top -- 16 mil Bottom

Gap= 10 mil Top -- 10 mil Bottom

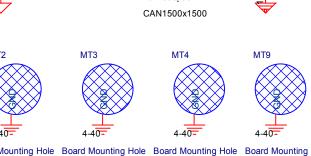
W= 20 mil Top -- 7 mil Layer 3

ISO= 50 mil - 0.050"

RF 50ohm Microstrip



Dimension 1.5 x 1.5 x 0.5 inches CAN1500x1500



Board Connectors

J1: RJ45 Jack POE- Power and Communication

J5: SMA RF1 OUT Tx/Rx

J8: 2.5x5.5mm Barrel Power Jack+12-24VDC @2A

J10: I/O 20pin 2x10 SAMTEC IPL111001LDRAK

J9: USB A Receptacle R/A VERT BSU communication

J12: 9-pin DSUB plug RS232 Communication

J13: Vert Mini B USB ATMEL SAM3X8C FLASH

U21: iMX6 SOM Connector

J22: FFC Label 8 pin Locking

J23: SD Card for SOM BOOT and Image Load

J14: RJ45 RA SHIELDED NO LED SPI Interboard

J15: RJ45 RA SHIELDED NO LED SPI Interboard

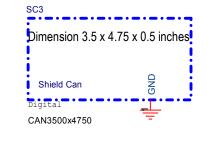
Ethernet 100ohm Diff. Pair

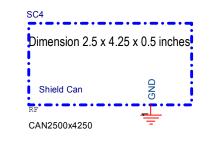
Equal Length

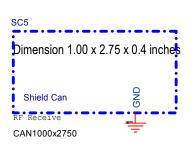
W= 16 mil Top -- 16 mil Bottom

Gap= 16 mil Top -- 16 mil Bottom

ISO= 60 mil - 0.060"







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RFC Reader Integrated BSU

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PCB Stackup

Option Finished August 20, 2014

FR408HR Dk=3.7 Df=0.009

Revision History

-122 Rev 01 Initial Design October 2013 Finished Nov 22, 2013

-123 Rev 01 Modify -122 Rev 05 for Four Port Standalone Reader

-122 Rev 02 Annotated Design January 2013 Finished Mar 25, 2014

-127 Rev 01 Modify -123 Rev 01 (4-Port) for Integrated BSU/Reader

Total Height 65mil - 0.065"

Core 10mil

Prepreg 8mil

(2x3313-57)

Prepreg 4mil

(1x3313-55)

Prepreg 8mil

(2x3313-57)

01

Core 10mil (2x2116)

Core 8mil

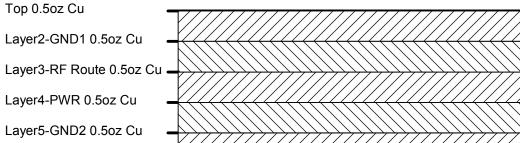
(2x3313)

(2x2116)

Core 8mil

(2x3313)





Layer6-Route1 0.5oz Cu

Board

Layer7-Route2 0.5oz Cu

Bottom-GND 0.5oz Cu

PLATED UP 1.0 oz TO APPROX 1.5mil

50 Ohm VIA - 13 mil hole, 20 mil pad top and inner, and bottom, 8 mil isolation from planes

